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wherein the improvement comprises the following steps:

10 (a) providing organic coatings, films, layers and residues that are either
photosensitive or non-photosensitive organic materials and are selected from the group con-
sisting of polymerized photoresists, paints, resins, single and multilayer organic polymers, or-
gano-metallic complexes, positive optical photoresist, negative optical photoresist, electron-
beam photoresists, X-ray photoresists, ion-beam photoresists, ion-implanted photoresists, and
other hardened photoresists, wherein said organic polymers are selected from the group con-
15 sisting of polyimides, copolyimides, polyamides, polyamide-imides, fluorinated polyimides,
poly(arylenethers), fluorinated poly(arylenethers), perfluorinated alkylene oxides, parylene
(N, C, D, or F type), poly(phenylquin-oxalines), poly-naphthalene, poly-fluorinated
naphthalene, benzocyclobutene (BCB), amorphous fluoropolymers, such as polytetrafluoro-
ethylene, perfluorocyclobutane aromatic ether (PFCB), polynorbornene, and fluorinated car-
20 bon, and wherein said substrate consists of at least one portion of a device selected from the
group consisting of semiconductor devices and wafers, [ceramic devices,] liquid crystal dis-
play devices, flat-panel displays, printed circuit boards, magnetic read/write heads, thin-film
read/write heads;

25 (b) subjecting said organic coatings, films, layers, or residues of step (a) to a
precursor chemical or physical treatment prior to step (1) so as to prepare said organic coat-
ings, films, layers, or residues for exposure to gaseous sulfur trioxide for facilitating the reac-
tion of said sulfur trioxide with the organic coatings, films, layers or residues to be removed;

30 (c) carrying out said step (1) so that said water-free, gaseous sulfur trioxide re-
acts with said organic coatings, films, layers, and residues to form physically or chemically
altered organic material;

(d) carrying out said step (2) to remove said altered organic material from said
substrates; and

35 (e) subjecting said organic coatings, films, layers, or residues to a chemical or
physical post-rinse treatment subsequent to step (2) to remove any residual organic material
from said substrates remaining after said solvent rinse.

Please consider canceling Claim 5, without prejudice.